

Plans in Bonn



Overall R&D goal: contribute to development of a pixel-based advanced endplate „SiTPC“

together with NIKHEF, Saclay, German Cluster (Fr,Mz,Si)

Immediate goals:

- „EUDET module“ (3-GEM with 8 Timepix) into LP in June
- High B-field (5T) test of 3GEM+TP at DESY (June)
- Pixel-size optimization (postprocessing at IZM Berlin) (+Freiburg)
- Ingrid development at IZM (masks produced, expect Ingrids + GEM Grids back end may(?))
- Chip development (with NIKHEF): gossipo3

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Mid/Longterm Goals:

- customized FPGA readout for Timepix (Mainz)
- comparison of Pix+GEM / Pix+Ingrid → focus on one
- establish Ingrid „mass“ (wafer) production at IZM
- realistic pixel-based endplate design
- contribute to chip development

Software?